PCN Number:		20200513002					PCN Date:		May 15, 2020		
Title: Da	LMG3410R070, LMG3411R070										
Customer Contact: PCN Manager							Dep	Dept: Quality Services			
Proposed 1st Ship Date: Aug.			15, 2020								
Change Type:											
Assembly Site			Design					Wafer Bump Site			
Assembly Process			\boxtimes	□ Data Sheet □				Wafer Bump Material			
Assembly Materials			Щ	Part number change				Wafer Bump Process			
Mechanical Specification			Щ	Test Site				Wafer Fab Site			
Packing/Shipping/Labeling				Test Process			Щ	Wafer Fab Materials			
								Wafer Fab Process			
Notification Details											
Description of Change:											
Texas Instruments Incorporated is announcing an information only notification.											
The product datasheet(s) is being updated as summarized below.											
TEXAS LMG3410R070, LMG3411R070 INSTRUMENTS											
Instruments									LMG3410R070, LMG3411R070		
SNOSD10F - APRIL 2016-REVISED MAY 2020											
Changes from Revision E (October 2018) to Revision F											
Deleted max drain-source leakage current6											
Added test condition for I _{trip}											
uip											
The datasheet number will be changing.											
Device Family			Change From:					Char	nge To:		
LMG3410R070, LMG3411R070				SNOSD10					SD10F		
http://www.ti.com/product/LMG3410R070											
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
Electrical specification performance changes as indicated above.											
Changes to product identification resulting from this PCN:											
None.											
Product Af	fected:										
LMG3410R	070RWHR	LM	IG3410)R0	70RWHT	LMG3411R070RWHR LMG3411R070RWHT					

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
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